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01/11/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10043946	FILING DATE 01/11/2002	CLASS 438	SUBCLASS 666	EAU 2812	EXAMINER Lewis
**APPLICANTS: Paek Jong <u>257</u>					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: REPUBLIC OF KOREA 2001-02163 01/15/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO AMKOR-017A	
Verified and Acknowledged Examiners's initials					
TITLE : Semiconductor package with stacked dies					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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